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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10075293	FILING DATE 02/15/2002	CLASS 257	SUBCLASS 758	GAU 2845	EXAMINER Vikram TRINH
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Wang Shuo-Cheng;

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****CONTINUING DATA VERIFIED:**

No

**** FOREIGN APPLICATIONS VERIFIED:**

TAIWAN 90-113556 02/15/2002

yes

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed

☒ yes ☐ no

35 USC 119 conditions met

☒ yes ☐ no

Verified and Acknowledged Examiners's initials

WZ 11/29/02

ATTORNEY DOCKET NO

YEHC3010/EM

TITLE : Method of reducing thick film stress of spin-on dielectric and the resulting sandwich dielectric structure

U.S. DEPT. OF COMM /PAT & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED

Assistant Examiner

ISSUE FEE

Amount Due

Date Paid



TERMINAL

DISCLAIMER

Primary Examiner

PREPARED FOR ISSUE

CLAIMS ALLOWED

Total Claims

Print Claim for
O.G.

DRAWING

Sheets Drawg.

Figs. Drawg.

Print Fig.

Application Examiner

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